

East 8 USPB USPT, WPID, JPO

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	225519	dehydrat\$ or "de hyrdat\$" or anhydrous	US-PGPUB; USPAT	OR	OFF	2005/05/11 13:32
L2	213300	sulfuric or sulphuric or ("h2so4" or "h.sub.2" with "so.sub.4")	US-PGPUB; USPAT	OR	ON	2005/05/11 13:26
L3	2418066	etch\$ or patern\$ or remov\$	US-PGPUB; USPAT	OR	ON	2005/05/11 13:24
L4	368	1 with 2 with 3	US-PGPUB; USPAT	OR	ON	2005/05/11 11:22
L5	213300	sulfuric or sulphuric or ("h2so4" or ("h.sub.2" with "so.sub.4"))	US-PGPUB; USPAT	OR	ON	2005/05/11 11:05
L6	81345	sulfuric or sulphuric or ("h2so4" or ("h.sub.2" with "so.sub.4"))	JPO; DERWENT	OR	ON	2005/05/11 11:05
L7	89929	dehydrat\$ or "de hyrdat\$" or anhydrous	JPO; DERWENT	OR	OFF	2005/05/11 11:05
L8	1670960	etch\$ or patern\$ or remov\$	JPO; DERWENT	OR	ON	2005/05/11 11:05
L9	655	6 and 7 and 8	JPO; DERWENT	OR	ON	2005/05/11 11:06
L10	124	6 with 7 with 8	JPO; DERWENT	OR	ON	2005/05/11 11:06
L11	252551	viscosit\$ or thixo\$ or thicken\$	JPO; DERWENT	OR	ON	2005/05/11 11:08
L12	42304	viscous\$	JPO; DERWENT	OR	ON	2005/05/11 11:06
L13	3	10 and (11 or 12)	JPO; DERWENT	OR	ON	2005/05/11 11:07
L14	121	10 not 13	JPO; DERWENT	OR	ON	2005/05/11 11:09
L15	421603	viscosit\$ or thixo\$ or thicken\$	US-PGPUB; USPAT	OR	ON	2005/05/11 11:08
L16	2	4 same 15	US-PGPUB; USPAT	OR	ON	2005/05/11 11:08
L17	366	4 not 16	US-PGPUB; USPAT	OR	ON	2005/05/11 11:22
L18	28	17 and (semiconduct\$ or wafer\$ or chip\$)	US-PGPUB; USPAT	OR	ON	2005/05/11 13:03
L19	340	4 not 18	US-PGPUB; USPAT	OR	ON	2005/05/11 11:23
L20	28	4 not 19	US-PGPUB; USPAT	OR	ON	2005/05/11 11:32
L21	338	4 not (20 or 16)	US-PGPUB; USPAT	OR	ON	2005/05/11 11:32
L22	8	21 and (etch\$ or patern\$ or remov\$.ti.	US-PGPUB; USPAT	OR	ON	2005/05/11 12:53

L23	330	21 not 22	US-PGPUB; USPAT	OR	ON	2005/05/11 12:44
L24	1332256	water or "h2o" or ("h.sub.2" with o)	US-PGPUB; USPAT	OR	ON	2005/05/11 13:27
L25	0	"remov\$ water" or "remov\$ h2o"	US-PGPUB; USPAT	OR	ON	2005/05/11 13:22
L26	0	"remov\$ water"	US-PGPUB; USPAT	OR	ON	2005/05/11 12:46
L27	332751	remov\$ with 24	US-PGPUB; USPAT	OR	ON	2005/05/11 12:47
L28	5196	2 with 27	US-PGPUB; USPAT	OR	ON	2005/05/11 12:47
L29	442	28 with (etch\$ or patern\$)	US-PGPUB; USPAT	OR	ON	2005/05/11 12:47
L30	440	29 not 4	US-PGPUB; USPAT	OR	ON	2005/05/11 12:47
L31	374	30 and (semiconduct\$ or wafer\$ or chip\$)	US-PGPUB; USPAT	OR	ON	2005/05/11 13:03
L32	130	29 same (semiconduct\$ or wafer\$ or chip\$)	US-PGPUB; USPAT	OR	ON	2005/05/11 12:50
L33	245	31 not 32	US-PGPUB; USPAT	OR	ON	2005/05/11 12:49
L34	15	32 and (etch\$ or patern\$ or remov\$).ti.	US-PGPUB; USPAT	OR	ON	2005/05/11 13:15
L35	12	33 and (etch\$ or patern\$ or remov\$).ti.	US-PGPUB; USPAT	OR	ON	2005/05/11 13:00
L36	1109492	condens\$ or extract\$ or evaporat\$	US-PGPUB; USPAT	OR	ON	2005/05/11 13:27
L37	289338	36 with 24	US-PGPUB; USPAT	OR	ON	2005/05/11 13:01
L38	21476	2 with 3	US-PGPUB; USPAT	OR	ON	2005/05/11 13:01
L39	1573	37 same 38	US-PGPUB; USPAT	OR	ON	2005/05/11 13:02
L40	841	37 with 38	US-PGPUB; USPAT	OR	ON	2005/05/11 13:02
L41	105	39 and (semiconduct\$ or wafer\$ or chip\$)	US-PGPUB; USPAT	OR	ON	2005/05/11 13:25
L42	1468	39 not 41	US-PGPUB; USPAT	OR	ON	2005/05/11 13:04
L43	105	39 not 42	US-PGPUB; USPAT	OR	ON	2005/05/11 13:13
L44	9	2 with 3 with neat	US-PGPUB; USPAT	OR	ON	2005/05/11 13:14
L45	1784	3 with neat	US-PGPUB; USPAT	OR	ON	2005/05/11 13:14

L46	168	45 and (semiconduct\$ or wafer\$ or chip\$)	US-PGPUB; USPAT	OR	ON	2005/05/11 13:14
L47	3	46 and (etch\$ or patern\$ or remov\$).ti.	US-PGPUB; USPAT	OR	ON	2005/05/11 13:35
L48	382	45 same 24	US-PGPUB; USPAT	OR	ON	2005/05/11 13:19
L49	29	46 and 48	US-PGPUB; USPAT	OR	ON	2005/05/11 13:22
L50	0	"remov\$ water" or "remov\$ h2o"	JPO; DERWENT	OR	ON	2005/05/11 13:23
L51	0	"remov\$ h.sub.2"	JPO; DERWENT	OR	ON	2005/05/11 13:23
L52	1670960	etch\$ or patern\$ or remov\$	JPO; DERWENT	OR	ON	2005/05/11 13:24
L53	171	52 with neat	JPO; DERWENT	OR	ON	2005/05/11 13:24
L54	7	53 and (semiconduct\$ or wafer\$ or chip\$)	JPO; DERWENT	OR	ON	2005/05/11 13:29
L55	81345	sulfuric or sulphuric or ("h2so4" or "h.sub.2" with "so.sub.4")	JPO; DERWENT	OR	ON	2005/05/11 13:26
L56	5	55 with neat	JPO; DERWENT	OR	ON	2005/05/11 13:26
L57	898271	condens\$ or extract\$ or evaporat\$	JPO; DERWENT	OR	ON	2005/05/11 13:27
L58	1890536	water or "h2o" or ("h.sub.2" with o)	JPO; DERWENT	OR	ON	2005/05/11 13:27
L59	132763	57 with 58	JPO; DERWENT	OR	ON	2005/05/11 13:28
L60	167106	52 with 58	JPO; DERWENT	OR	ON	2005/05/11 13:28
L61	14123	52 with 59	JPO; DERWENT	OR	ON	2005/05/11 13:28
L62	562	55 and 61	JPO; DERWENT	OR	ON	2005/05/11 13:28
L63	287	61 and (semiconduct\$ or wafer\$ or chip\$)	JPO; DERWENT	OR	ON	2005/05/11 13:32
L64	12	62 and 63	JPO; DERWENT	OR	ON	2005/05/11 13:29
L65	89929	dehydrat\$ or "de hyrdat\$" or anhydrous	JPO; DERWENT	OR	OFF	2005/05/11 13:32
L66	8431	57 with 65	JPO; DERWENT	OR	OFF	2005/05/11 13:32
L67	770	52 with 66	JPO; DERWENT	OR	OFF	2005/05/11 13:32
L68	13	67 and (semiconduct\$ or wafer\$ or chip\$)	JPO; DERWENT	OR	ON	2005/05/11 13:33

L69	122	67 and (etch\$ or patern\$ or remov\$).ti.	JPO; DERWENT	OR	ON	2005/05/11 13:35
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